

AbstractA SYSTEM FOR RELIABLY REMOVING HEAT
FROM A SEMICONDUCTOR JUNCTION

The system includes a heat sink member which is permanently attached to a semiconductor integrated circuit which is part of an integrated circuit board assembly, which in turn is part of an electronic equipment unit. A mounting member is positioned in the equipment chassis, adjacent to the integrated circuit board assembly, the mounting member having two spaced openings therein through which inwardly curved end portions of a spring clip extend. The end portions are adapted to conveniently and readily receive and release the heat sink in a low thermal resistance relationship. Hence, individual circuit boards may be removed from the equipment and replaced, without disturbing the desired thermal conductivity between the integrated circuit on the board and the equipment chassis. When the heat sink is operatively received by the end portions of the clip, heat is conducted away from the semiconductor junctions in the integrated circuit to the ambient air outside of the equipment chassis.